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PATENT APPLICATION
DOCKET NO.: 9903-078
CLIENT NO.: S02US013D

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): Young-Hee SONG, et al.
Serial No.: 10/651,813 Examiner: Willams, Alexander O.
Filing Date: August 28, 2003 Group Art Unit: 2826
Title: SEMICONDUCTOR CHIP HAVING BOND PADS AND MULTI-CHIP PACKAGE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

This Information Disclosure Statement is submitted:

- ☐ under 37 CFR 1.97 (b); or
(Within three months of filing national application; or date of entry of International application;
or before mailing date of first office action on the merits; whichever occurs last)
- ☒ under 37 CFR 1.97 (c) together with either a:
☒ Statement under 37 CFR 1.97 (e), or
☐ a \$180 fee under 37 CFR 1.17 (p); or
(After mailing of first Office Action, but prior to Notice of Allowance or Final Office Action)
- ☐ under 37 CFR 1.97 (d) together with:
☐ Statement under 37 CFR 1.97 (e), and
☐ a \$180.00 fee set forth in 37 CFR 1.17 (p).

(Filed after final action or notice of allowance, whichever occurs first, but before payment of the issue fee)

☒ Applicant(s) submit herewith Form PTO 1449- Information Disclosure Citation together with copies of patents, publications or other information of which applicant(s) are aware, which applicant(s) believe(s) may be material to the examination of this application and for which there may be a duty to disclose in accordance with 37 CFR 1.56.

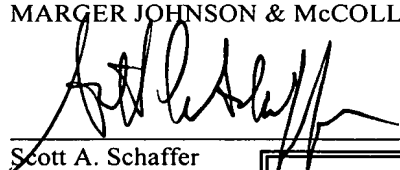
It is requested that the information disclosed herein be made of record in this application.

Any deficiency or overpayment should be charged or credited to deposit account number 13-1703. A duplicate copy of this sheet is enclosed.

Customer No. 20575

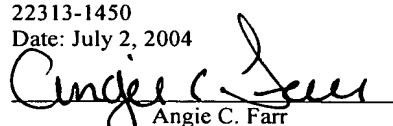
Respectfully submitted,

MARGER JOHNSON & McCOLLOM, P.C.



Scott A. Schaffer
Reg. No. 38,610

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I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450
Date: July 2, 2004

Angie C. Farr



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INFORMATION DISCLOSURE CITATION
FORM PTO-1449 (Continued)

U.S. PATENT DOCUMENTS

<u>Exam Init</u>	<u>Ref</u>	<u>Document Number</u>	<u>Issue Date</u>	<u>Name</u>	<u>Class</u>	<u>Sub Class</u>
_____	_____	4,723,197	Feb. 2, 88	Takiar et al.		
_____	_____	5,502,289	Mar. 26, 96	Takiar et al		
_____	_____	5,834,844	Nov. 10, 98	Akagawa et al		
_____	_____	6,175,149	Jan. 16, 01	Akram		
_____	_____	6,498,396 B1	Dec. 24, 02	Arimo		

FOREIGN PATENT DOCUMENTS

<u>Exam Init</u>	<u>Ref</u>	<u>Document Number</u>	<u>Publication Date</u>	<u>Country</u>	<u>Name</u>
_____	_____	DE 19610302 A1	Oct. 2, 96	Germany, (Corresponds to US 6,498,396 B1)	
_____	_____	EP 1094517 A2	Apr. 25, 01	Europe	
_____	_____	EP 0221496 A2	May 13, 87	Europe	
_____	_____	2000058743 A	Feb. 25, 00	Japan	

OTHER DOCUMENTS

<u>Exam Init</u>	<u>Ref</u>	<u>Author, Title, Date, Pertinent Pages, Etc.)</u>
_____	_____	Yasunaga, et al. "Chip Scale Package: "A Light Dressed LSI Chip" IEEE transactions on component, packaging and Manufacturing technology part A. Vol. 18, No. 3. September 1995, pp. 451-457

Examiner: _____

Date Considered: _____



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STATEMENT ON FILING INFORMATION DISCLOSURE STATEMENT
(37 CFR 1.97(e))

I, Scott A. Schaffer, the person signing below state that:

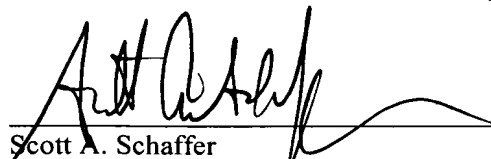
Some of the information contained in the Information Disclosure Statement submitted herewith was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Statement.

Applicant respectfully requests consideration of the accompanying Information Disclosure Statement.

The person making this Statement is the attorney who signs below on the basis of the information in the attorney's file.

Respectfully submitted,

MARGER JOHNSON & McCOLLOM, P.C.



Scott A. Schaffer
Reg. No. 38,610

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